REVISIONS		
#	DESCRIPTION	DATE

NOTES

Allow clearance for finger squeeze access from the two sides shown.

No tracks or vias in the shaded keepout area.

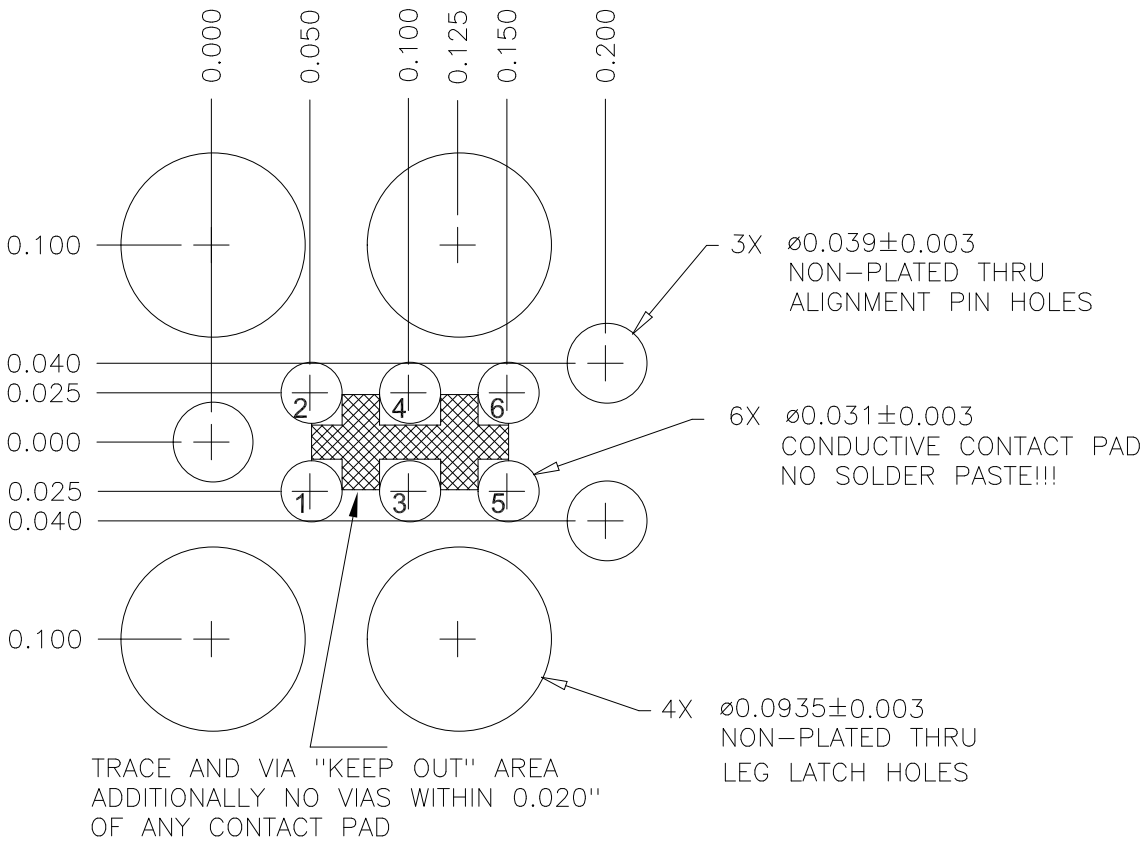
No other track or signal within 0.020" of any contact pad.

Do not allow solder paste on the contact pads. It is essential to eliminate any hole in the solder paste–mask (solder stencil) layer. If this is not possible make the contact pads thru–hole with finished hole size of 0.008" or less.

Leg and alignment holes may be plated and used as vias but ensure minimum finished hole size meets specified tolerances.

To prevent purchasing confusion, please specify DNL in your BOM!

Allow finger access from this side



Allow finger access from this side

Microchip ICD / ICSP SIGNALS
Pin 1: –MCLR/Vpp
Pin 2: Vdd
Pin 3: Ground
Pin 4: PGD (ICSPDAT)
Pin 5: PGC (ICSPCLK)
Pin 6: Unused or LVP

CUSTOMER:

FILE:

INFORMATION CONTAINED HEREIN IS THE PROPERTY OF TAG–CONNECT. THIS INFORMATION SHALL NOT BE DISCLOSED BY THE RECIPIENT WITHOUT WRITTEN AUTHORIZATION FROM TAG–CONNECT, SAN BRUNO, CA.

UNLESS OTHERWISE NOTED DIMENSIONS ARE IN INCHES		
.XXX±	.XX±	ANGLE ±
.005	.01	1.5°

THIRD ANGLE PROJECTION

SCALE: 10:1

DRAWN PM / NS DATE 4/5/10

CHECKED DATE

www.TAG-CONNECT.com

TITLE TC2030–MCP–FP
FOOTPRINT FOR TC2030–MCP

SIZE		DWG. NO.	REV.
A	SHEET 1 OF 1		D